

## **AMENDMENTS TO THE SPECIFICATION**

Please add the following paragraph at page 1, before line 1:

### **--Cross Reference to Related Application**

This application is a continuation of co-pending U.S. Patent Application Serial No. 10/188,696 filed July 2, 2002 and entitled SINGLE LAYER CAPACITOR, the disclosure of which is incorporated herein by reference in its entirety as if completely set forth herein below.--

Please replace the paragraph beginning at page 33, line 1, with the following rewritten paragraph:

--A monolithic or essentially monolithic single layer capacitor with high structural strength and capacitance ~~that may be easily and inexpensively manufactured. To this end, sheets~~ Sheets of green-state ceramic dielectric material and ceramic/metal composite material are laminated together, diced into individual chips, and fired to sinter the ceramic together. The composite material ~~may comprise~~ contains an amount of metal sufficient to render the composite conductive whereby the composite may be used for one or both electrodes and for mounting the capacitor to the pc board. ~~Alternatively, the composite material may comprise~~ contain an amount of metal ~~insufficient to render the composite conductive but sufficient to act as seed points for an electroplating process wherein the composite is preferentially coated with conductive metal, and the coated composite is mounted~~ to the pc board and the coating provides an electrical connection to an internal electrode. By the present invention, vertically-oriented Vertically-oriented surface mountable capacitors and hybrid capacitors are provided. --